

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	964	solid adj electrolytic adj capacitor	US-PGPUB; USPAT	OR	OFF	2008/03/26 18:56
L2	54	(inductor near3 laminat\$4) with winding with magnetic	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/26 19:15
L3	162868	winding with coil	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/26 19:16
L4	1	1 and 2 and 3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/26 19:16
L5	1	1 and 2	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/26 19:16
L6	36	2 and 3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/26 19:17
L7	154549	magnetic with metal\$3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/26 19:18
L8	6	6 and 7	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/26 19:18
L9	4	@ad <= "20040507" and 8	US-PGPUB; USPAT	OR	ON	2008/03/26 19:18

L10	656	@ad <= "20040507" and 1	US-PGPUB; USPAT	OR	ON	2008/03/26 19:18
L11	27	@ad <= "20040507" and 6	US-PGPUB; USPAT	OR	ON	2008/03/26 19:21
L12	2	("20030169575").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/03/26 21:24
L13	2	("7193311").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/03/26 21:28
L14	237	10 and (multilayer or multi-layer or (multi adj layer) or laminat\$4)	US-PGPUB; USPAT	OR	ON	2008/03/26 21:37
L15	31286	wiring adj (board or substrate or PCB)	US-PGPUB; USPAT	OR	ON	2008/03/26 21:38
L16	25	14 and 15	US-PGPUB; USPAT	OR	ON	2008/03/26 21:38
L17	8	((("7057896") or ("20030015342") or ("20040056344") or ("5745984"))).PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/03/26 22:05
L18	12	((("7057896") or ("20030015342") or ("20040056344") or ("5745984") or ("7045391") or ("20030219969"))).PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/03/26 22:06
L19	2	("7193311").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/03/26 22:24
S23	11	("4372996" "5073814" "5161093" "5353498" "5386623" "5434751" "5745984" "5773899" "6110806" "6154366" "6162652").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2008/03/25 16:34
S24	8	("4783695" "5108825" "5169678" "5255431" "5353498" "5388328" "5546654" "5564181").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2008/03/25 16:34

S25	50098	(wiring\$2 or pattern\$2) with (multilayer or multilayer or (multi adj layer) or laminat\$4)	US-PGPUB; USPAT	OR	ON	2008/03/25 16:38
S26	13652	S25 and (die or IC or (integrated adj circuit) or chip or component or (semiconductor adj device)) and (capacitor or inductor or resistor or (passive adj (element or component)))	US-PGPUB; USPAT	OR	ON	2008/03/25 16:42
S27	13652	S25 and S26	US-PGPUB; USPAT	OR	ON	2008/03/25 16:42
S28	37533	(heatsink or sink or (cooling adj plate) or spreader or (metal adj plate)) with (die or IC or (integrated adj circuit) or chip or component or (semiconductor adj device))	US-PGPUB; USPAT	OR	ON	2008/03/25 16:43
S29	687	S27 and S28	US-PGPUB; USPAT	OR	ON	2008/03/25 16:43
S30	463	@ad <= "20040507" and S29	US-PGPUB; USPAT	OR	ON	2008/03/25 16:44
S31	4353	((361/760-764) or (361/766) or (361/795) or (361/709)).OCLS.	US-PGPUB; USPAT	OR	OFF	2008/03/25 16:47
S32	0	("13and14").PN.	US-PGPUB; USPAT	OR	OFF	2008/03/25 16:47
S33	44	S30 and S31	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/03/25 16:47
S34	11	("4677526" "4755910" "4949224" "4958258" "4996630" "5130768" "5262351" "5367434" "5650920" "5751555" "5877550").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2008/03/25 16:56
S35	14	("4539622" "4630172" "5001548" "5008734" "5012386" "5043796" "5109317" "5276586" "5323292" "5346118" "5355283" "5521435" "5541450" "5561323").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2008/03/25 17:01

S36	909	(361/748).CCLS.	US-PGPUB; USPAT	OR	OFF	2008/03/25 17:11
S38	7	S30 and S36	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/03/25 17:12
S39	7	@ad <= "20040507" and S38	US-PGPUB; USPAT	OR	ON	2008/03/25 17:12
S40	774	@ad <= "20040507" and S36	US-PGPUB; USPAT	OR	ON	2008/03/25 17:12
S41	164	S40 and S25	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/03/25 17:13
S42	11	S41 and S28	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/03/25 17:13
S43	400593	(wiring\$2 or pattern\$2) with (layer or substrate or board or PCB)	US-PGPUB; USPAT	OR	ON	2008/03/25 17:14
S44	93152	S43 and (die or IC or (integrated adj circuit) or chip or component or (semiconductor adj device)) and (capacitor or inductor or resistor or (passive adj (element or component)))	US-PGPUB; USPAT	OR	ON	2008/03/25 17:14
S45	3307	S44 and S28	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/03/25 17:15
S46	2313	@ad <= "20040507" and S45	US-PGPUB; USPAT	OR	ON	2008/03/25 17:16
S47	155725	"361"/\$.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/25 17:16

S48	519	S46 and S47	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/25 17:16
S49	11	("20010043130" "20020075106" "20020171157" "20030036020" "20030080836" "20030141105" "5325072" "6057600" "6538210" "6683512" "6714422").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2008/03/25 17:49
S50	6	("4931853" "5306670" "5422513" "5745984" "5998859" "6555906"). PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2008/03/25 17:51
S51	18674	((257/774) or (257/787- 795) or (257/698) or (257/687) or (257/723- 724) or (257/675) or (257/686) or (257/668) or (257/706-707) or (257/712) or (257/678)). OCLS.	US-PGPUB; USPAT	OR	OFF	2008/03/25 18:28
S52	469	S51 and S46	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/25 18:28
S53	469	@ad <= "20040507" and S52	US-PGPUB; USPAT	OR	ON	2008/03/25 18:29
S54	345	S53 not S48	US-PGPUB; USPAT	OR	ON	2008/03/25 18:29
S55	13	("5060045" "5231751" "5592735" "5640051" "6110806" "6156870" "6188127" "6459152" "6535398" "6570469" "6582991" "6731010" "6765299").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2008/03/25 18:54
S56	4	((("5353498") or ("20030015342"))).PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/03/25 19:12

S57	45959	((insulat\$4 or dielectric or resin or epoxy) near (film or layer)) with (powder or particle or filler)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/25 19:16
S58	410592	(resin or epoxy) with (powder or particle or filler)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/25 19:17
S59	28216	S57 and S58	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/25 19:17
S60	11442	(resin or epoxy) with (powder or particle or filler) with (conductor or pattern\$3 or wiring)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/25 19:18
S61	2953	S59 and S60	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/25 19:18
S62	1185	S61 and (multilayer or multi-layer or (multi adj layer) or laminat\$4)	US-PGPUB; USPAT	OR	ON	2008/03/25 19:19
S63	827	@ad <= "20040507" and S62	US-PGPUB; USPAT	OR	ON	2008/03/25 19:19
S64	96	S47 and S63	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/03/25 19:20
S65	3	((("20040201085") or ("7193311")).PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/03/25 20:05
S66	2	("7193311").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/03/25 20:07

S67	2	("6865089").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/03/25 20:19
S68	2	("20040160751").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/03/25 20:41
S69	7088	solid adj electrolytic adj capacitor	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/03/26 01:24

3/ 26/ 08 10:56:18 PM

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